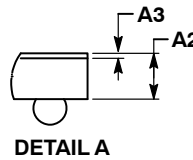
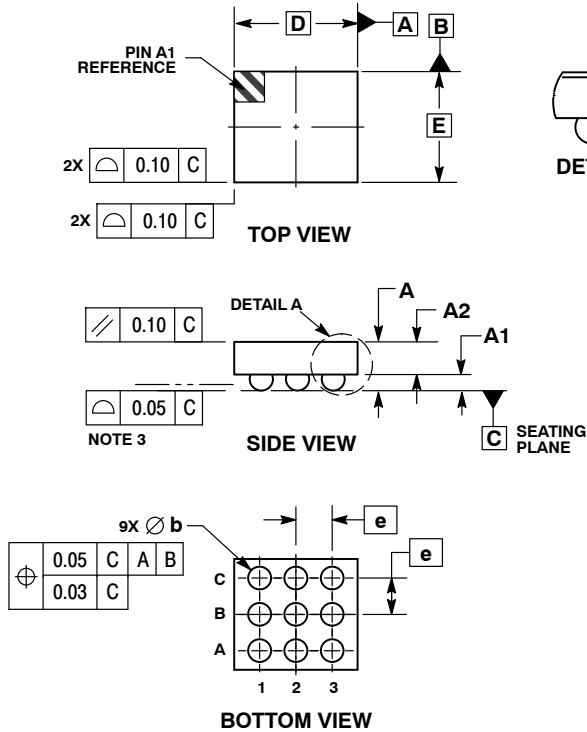




SCALE 4:1

WLCSP9, 1.36x1.22  
CASE 567GM  
ISSUE A

DATE 14 MAR 2013

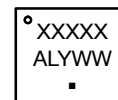


NOTES:

1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994.
2. CONTROLLING DIMENSION: MILLIMETERS.
3. COPLANARITY APPLIES TO THE SPHERICAL CROWNS OF THE SOLDER BALLS.

MILLIMETERS		
DIM	MIN	MAX
A	---	0.60
A1	0.17	0.23
A2	0.36	REF
A3	0.02	0.04
b	0.24	0.29
D	1.36	BSC
E	1.22	BSC
e	0.40	BSC

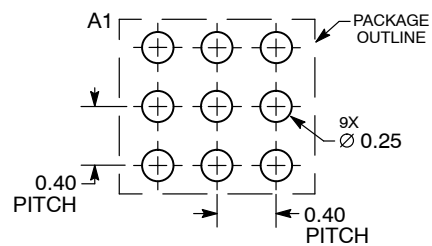
GENERIC  
MARKING DIAGRAM\*



- A = Assembly Location
- L = Wafer Lot
- Y = Year
- WW = Work Week
- = Pb-Free Package

\*This information is generic. Please refer to device data sheet for actual part marking.  
Pb-Free indicator, "G" or microdot "▪", may or may not be present.

RECOMMENDED  
SOLDERING FOOTPRINT\*



DIMENSIONS: MILLIMETERS

\*For additional information on our Pb-Free strategy and soldering details, please download the **onsemi** Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

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<b>DESCRIPTION:</b>	<b>WLCSP9, 1.36X1.22</b>	<b>PAGE 1 OF 1</b>

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